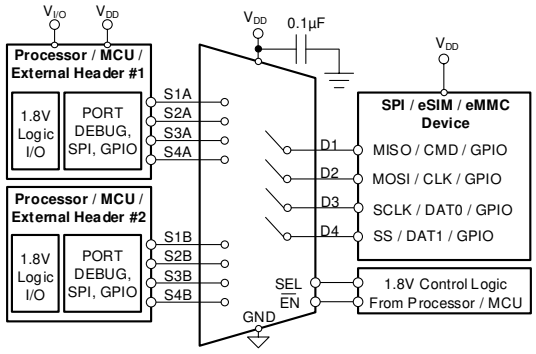
SN3257-Q1 1.8V ロジック搭載、車載用、5V、低伝搬遅延、2：1 (SPDT)、4 チャネル・スイッチ

1 特長

- 機能安全対応
  - 機能安全システムの設計に役立つ資料を利用可能
- 車載アプリケーション向けに AEC-Q100 認定済み
  - 温度グレード 1：-40℃～+125℃、T_A
- 広い電源電圧範囲：1.5V～5.5V
- 小さい伝搬遅延時間：78ps
- 低オン抵抗：5Ω
- 広帯域幅：2GHz
- 双方向の信号パス
- 電源電圧を超える入力電圧に対応
- 1.8V ロジック互換
- ロジック・ピンにプルダウン抵抗を内蔵
- フェイルセーフ・ロジック
- 最大 3.6V の信号の電源オフ保護

2 アプリケーション

- SPI 多重化
- I2S 多重化
- eSIM 多重化
- eMMC 多重化
- フラッシュ・メモリの共有
- バッテリ管理システム (BMS)
- テレマティクス制御ユニット (TCU)
- スマート・テレマティクス・ゲートウェイ
- 後部座席用エンターテインメント
- デジタル・コックピット処理装置
- 車載用ヘッド・ユニット
- 車載ナビゲーション
- ADAS ドメイン・コントローラ
- サラウンド・ビュー・システムの ECU
- オンボード・チャージャ (OBC) とワイヤレス・チャージャ



アプリケーションの例

3 概要

SN3257-Q1 は、短い伝播遅延で高速信号に対応できる車載グレードの CMOS (相補型金属酸化膜半導体) スイッチです。SN3257-Q1 は 4 チャネルの 2:1 (SPDT) スイッチ構成であるため、SPI、I2S などのマルチレーン・プロトコルに理想的です。このデバイスは、ソース (SxA、SxB) ピンとドレイン (Dx) ピンでの双方向アナログおよびデジタル信号をサポートしており、電源電圧を超えて、最大で V_{DD} x 2 (最大入出力電圧は 5.5V) の信号を通すことができます。

SN3257-Q1 は、すべてのチャネルを同時にイネーブル / ディスエーブルするために使用するアクティブ Low の $\overline{EN}$ ピンを備えています。$\overline{EN}$ ピンを Low にすると、SEL ピンの状態に基づいて 2 つのスイッチ経路のうち 1 つが選択されます。

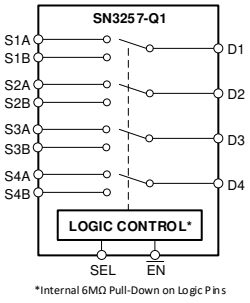
SN3257-Q1 の信号経路の最大 3.6V の電源オフ保護機能は、電源電圧が取り除かれたとき (V_{DD} = 0V) に絶縁を行います。この保護機能がない場合、内部 ESD ダイオード経由でスイッチから電源レールに電流が逆流し、システムに損傷を引き起こすおそれがあります。

フェイルセーフ回路により、電源ピンよりも前にロジック制御ピンに電圧が印加されるため、デバイスへの損傷の可能性が避けられます。ロジック制御入力はどちらも、スレッショルドが 1.8V ロジック互換であるため、TTL と CMOS の両方のロジックとの互換性が確保されます。ロジック・ピンにはプルダウン抵抗が内蔵されているため、外付け部品を省略でき、システムのサイズとコストを低減できます。

パッケージ情報 (1)

部品番号	パッケージ	本体サイズ (公称)
SN3257-Q1	PW (TSSOP、16)	5.00mm × 4.40mm
	DYY (SOT-23-THIN、16)	4.20mm × 2.00mm

(1) 利用可能なパッケージについては、データシートの末尾にあるパッケージ・オプションについての付録を参照してください。



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4 Revision History

資料番号末尾の英字は改訂を表しています。その改訂履歴は英語版に準じています。

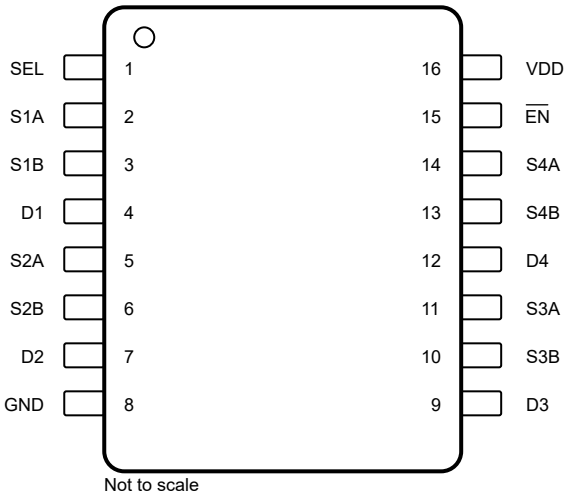
Changes from Revision C (December 2021) to Revision D (October 2022)	Page
• 帯域幅の仕様を 1.2GHz から 2GHz に更新	1

Changes from Revision B (January 2020) to Revision C (December 2021)	Page
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• 文書全体にわたって表、図、相互参照の採番方法を更新	1

Changes from Revision A (August 2016) to Revision B (January 2020)	Page
• ドキュメントのステータスを*事前情報*から*量産データに変更*	1

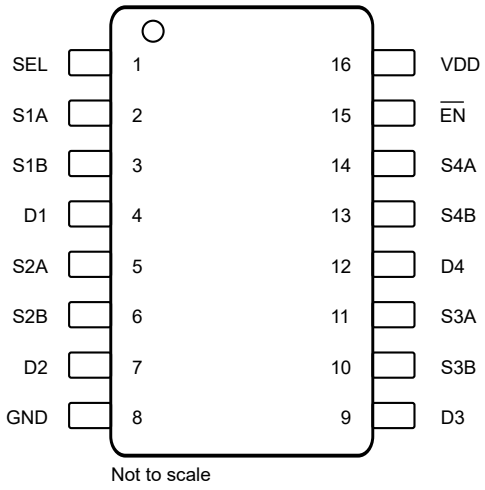
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5 Pin Configuration and Functions



Not to scale

図 5-1. PW Package, 16-Pin TSSOP (Top View)



Not to scale

図 5-2. DYY Package, 16-Pin SOT-23 (Top View)

表 5-1. Pin Functions

PIN		TYPE[1]	DESCRIPTION[2]
NAME	NO.		
SEL	1	I	Select pin: controls state of switches according to 表 8-1. Internal 6 MΩ pull-down to GND.
S1A	2	I/O	Source pin 1A. Can be an input or output.
S1B	3	I/O	Source pin 1B. Can be an input or output.
D1	4	I/O	Drain pin 1. Can be an input or output.
S2A	5	I/O	Source pin 2A. Can be an input or output.
S2B	6	I/O	Source pin 2B. Can be an input or output.
D2	7	I/O	Drain pin 2. Can be an input or output.
GND	8	P	Ground (0 V) reference
D3	9	I/O	Drain pin 3. Can be an input or output.
S3B	10	I/O	Source pin 3B. Can be an input or output.
S3A	11	I/O	Source pin 3A. Can be an input or output.
D4	12	I/O	Drain pin 4. Can be an input or output.
S4B	13	I/O	Source pin 4B. Can be an input or output.
S4A	14	I/O	Source pin 4A. Can be an input or output.
$\overline{EN}$	15	I	Active low enable: When this pin is high, all switches are turned off. When this pin is low, SEL pin controls the signal path selection. Internal 6 MΩ pull-down to GND.
VDD	16	P	Positive power supply. This pin is the most positive power-supply potential. For reliable operation, connect a decoupling capacitor ranging from 0.1 µF to 10 µF between V_{DD} and GND.

(1) I = input, O = output, I/O = input and output, P = power
(2) Refer to セクション 8.4 for what to do with unused pins.

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6 Specifications

6.1 Absolute Maximum Ratings

Over operating free-air temperature range (unless otherwise noted)(1) (2) (3)

		MIN	MAX	UNIT
V_{DD}	Supply voltage	–0.5	6	V
V_{SEL} or V_{EN}	Logic control input pin voltage (SEL or $\overline{EN}$)	–0.5	6	V
I_{SEL} or I_{EN}	Logic control input pin current (SEL or $\overline{EN}$)	–30	30	mA
V_S or V_D	Source or drain pin voltage	–0.5	6	V
I_S or $I_{D\ (CONT)}$	Source and drain pin continuous current: (SxA, SxB, Dx)	–25	25	mA
T_{stg}	Storage temperature	–65	150	°C
T_J	Junction temperature		150	°C

(1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions*. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
(2) The algebraic convention, whereby the most negative value is a minimum and the most positive value is a maximum.
(3) All voltages are with respect to ground, unless otherwise specified.

6.2 ESD Ratings

			VALUE	UNIT
$V_{(ESD)}$	Electrostatic discharge	Human body model (HBM), per AEC Q100-002(1) HBM ESD Classification Level 2	±2000	V
		Charged device model (CDM), per AEC Q100-011 CDM ESD Classification Level C4B	±750	

(1) AEC Q100-002 indicates that HBM stressing shall be in accordance with the ANSI/ESDA/JEDEC JS-001 specification.

6.3 Recommended Operating Conditions

		MIN	MAX	UNIT
V_{DD}	Supply voltage	1.5	5.5	V
V_S or V_D	Signal path input or output voltage (source or drain pin), $V_{DD} \geq 1.5$ V(1)	0	V_{DD} x 2	V
V_{S_off} or V_{D_off}	Signal path input or output voltage (source or drain pin), $V_{DD} < 1.5$ V(2)	0	3.6	V
V_{SEL} or V_{EN}	Logic control input voltage ($\overline{EN}$, SEL)	0	5.5	V
I_S or $I_{D\ (CONT)}$	Source and drain pin continuous current: (SxA, SxB, Dx)	–25	25	mA
T_A	Ambient temperature	–40	125	°C

(1) Device input/output can operate up to V_{DD} x 2, with a maximum input/output voltage of 5.5 V.
(2) V_{S_off} and V_{D_off} refers to the voltage at the source or drain pins when supply is less than 1.5 V.

6.4 Thermal Information

THERMAL METRIC(1)		DEVICE PW (TSSOP) 16 PINS	DEVICE DYY (SOT-23) 16 PINS	UNIT
$R_{\theta JA}$	Junction-to-ambient thermal resistance	117.4	123.0	°C/W
$R_{\theta JC(top)}$	Junction-to-case (top) thermal resistance	47.9	70.5	°C/W
$R_{\theta JB}$	Junction-to-board thermal resistance	63.7	50.4	°C/W
Ψ_{JT}	Junction-to-top characterization parameter	6.9	5.0	°C/W
Ψ_{JB}	Junction-to-board characterization parameter	63.1	50.3	°C/W
$R_{\theta JC(bot)}$	Junction-to-case (bottom) thermal resistance	N/A	N/A	°C/W

(1) For more information about traditional and new thermal metrics, see the Semiconductor and IC Package Thermal Metrics application report.

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6.5 Electrical Characteristics

V_{DD} = 1.5 V to 5.5 V, GND = 0V, T_A = –40°C to +125°C
Typical values are at V_{DD} = 3.3 V, T_A = 25°C, (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
POWER SUPPLY						
V_{DD}	Power supply voltage		1.5		5.5	V
I_{DD}	Active supply current	V_{SEL} = 0 V, 1.4 V or V_{DD} V_S = 0 V to 5.5 V		40	68	µA
$I_{DD_STANDBY}$	Supply current when disabled	V_{EN} = 1.4 V or V_{DD} V_S = 0 V to 5.5 V		7.5	15	µA
DC CHARACTERISTICS						
R_{ON}	On-resistance	V_S = 0 V to V_{DD}×2 $V_{S(max)}$ = 5.5 V I_{SD} = 8 mA Refer to ON-State Resistance Figure		2	5	Ω
ΔR_{ON}	On-resistance match between channels	V_S = V_{DD} I_{SD} = 8 mA Refer to ON-State Resistance Figure		0.07	0.8	Ω
$R_{ON\ (FLAT)}$	On-resistance flatness	V_S = 0 V to V_{DD} I_{SD} = 8 mA Refer to ON-State Resistance Figure		1	2.5	Ω
I_{POFF}	Powered-off I/O pin leakage current	V_{DD} = 0 V V_S = 0 V to 3.6 V V_D = 0 V Refer to Ipoff Leakage Figure	–8	0.01	8	µA
$I_{S(OFF)}$ $I_{D(OFF)}$	OFF leakage current	Switch Off V_D = 0.8×V_{DD} / 0.2×V_{DD} V_S = 0.2×V_{DD} / 0.8×V_{DD} Refer to Off Leakage Figure	–900	0.03	900	nA
$I_{D(ON)}$ $I_{S(ON)}$	ON leakage current	Switch On V_D = 0.8×V_{DD} / 0.2×V_{DD}, S pins floating or V_S = 0.8×V_{DD} / 0.2×V_{DD}, D pins floating Refer to On Leakage Figure	–900	0.01	900	nA
LOGIC INPUTS						
V_{IH}	Input logic high		1.2		5.5	V
V_{IL}	Input logic low		0		0.45	V
I_{IH}	Input high leakage current	V_{SEL} = 1.8 V, V_{DD}		1	±2	µA
I_{IL}	Input low leakage current	V_{SEL} = 0 V		0.2	±2	µA
R_{PD}	Internal pull-down resistor on logic pins			6		MΩ
C_I	Logic input capacitance	V_{SEL} = 0 V, 1.8 V or V_{DD} f = 1 MHz		3		pF

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6.6 Dynamic Characteristics

V_{DD} = 1.5 V to 5.5 V, GND = 0 V, T_A = –40°C to +125°C
Typical values are at V_{DD} = 3.3 V, T_A = 25°C, (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP	MAX	UNIT
C_{OFF}	Source and drain off capacitance	V_S = 2.5 V V_{SEL}= 0 V f = 1 MHz Refer to Capacitance Figure	Switch OFF		4		pF
C_{ON}	Source and drain on capacitance	V_S = 2.5 V V_{SEL}= 0 V f = 1 MHz Refer to Capacitance Figure	Switch ON		8		pF
Q_C	Charge Injection	V_S = V_{DD}/2 R_S = 0 Ω, C_L =1 nF Refer to Charge Injection Figure	Switch ON		3.5		pC
O_{ISO}	Off isolation	R_L = 50 Ω f = 100 kHz Refer to Off Isolation Figure	Switch OFF		–90		dB
		R_L = 50 Ω f = 1 MHz Refer to Off Isolation Figure	Switch OFF		–75		dB
X_{TALK}	Channel to Channel crosstalk	R_L = 50 Ω f = 100 kHz Refer to Crosstalk Figure	Switch ON		–90		dB
BW	Bandwidth	R_L = 50 Ω Refer to Bandwidth Figure	Switch ON		2		GHz
I_{LOSS}	Insertion loss	R_L = 50 Ω f = 1 MHz Refer to Bandwidth Figure	Switch ON		–0.12		dB

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6.7 Timing Requirements

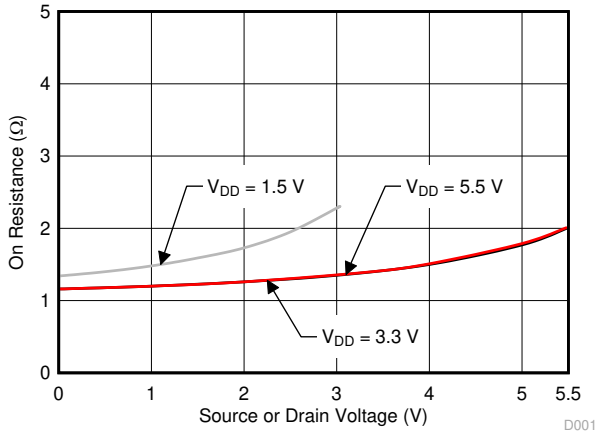
V_{DD} = 1.5 V to 5.5 V, GND = 0V, T_A = –40°C to +125°C
Typical values are at V_{DD} = 3.3 V, T_A = 25°C, (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	NOM	MAX	UNIT
t_{TRAN}	Transition time from control input	V_{DD} = 2.5 V to 5.5 V V_S = V_{DD} R_L = 200 Ω, C_L = 15 pF Refer to Transition Timing Figure		160	350	ns
t_{TRAN}	Transition time from control input	V_{DD} < 2.5 V V_S = V_{DD} R_L = 200 Ω, C_L = 15 pF Refer to Transition Timing Figure		180	580	ns
$t_{ON(EN)}$	Device turn on time from enable pin	V_S = V_{DD} R_L = 200 Ω, C_L = 15 pF Refer to Ton(EN) and Toff(EN) Figure		12	35	µs
$t_{OFF(EN)}$	Device turn off time from enable pin	V_S = V_{DD} R_L = 200 Ω, C_L = 15 pF Refer to Ton(EN) and Toff(EN) Figure		50	95	ns
$t_{ON(VDD)}$	Device turn on time (V_{DD} to output)	V_S = 3.6 V V_{DD} rise time = 1 µs R_L = 200 Ω, C_L = 15 pF Refer to Ton(vdd) and Toff(vdd) Figure		20	60	µs
$t_{OFF(VDD)}$	Device turn off time (V_{DD} to output)	V_S = 3.6 V V_{DD} fall time = 1 µs R_L = 200 Ω, C_L = 15 pF Refer to Ton(vdd) and Toff(vdd) Figure		1.2	2.7	µs
$t_{OPEN\ (BBM)}$	Break before make time	V_S = 1 V R_L = 200 Ω, C_L = 15 pF Refer to Topen(BBM) Figure	0.5			ns
$t_{SK(P)}$	Inter-channel skew – SOT-23 (DYY)	Refer to Tsk Figure		10		ps
$t_{SK(P)}$	Inter-channel skew – TSSOP (PW)	Refer to Tsk Figure		18		ps
t_{PD}	Propagation delay – SOT-23 (DYY)	Refer to Tpd Figure		78		ps
t_{PD}	Propagation delay – TSSOP (PW)	Refer to Tpd Figure		95		ps

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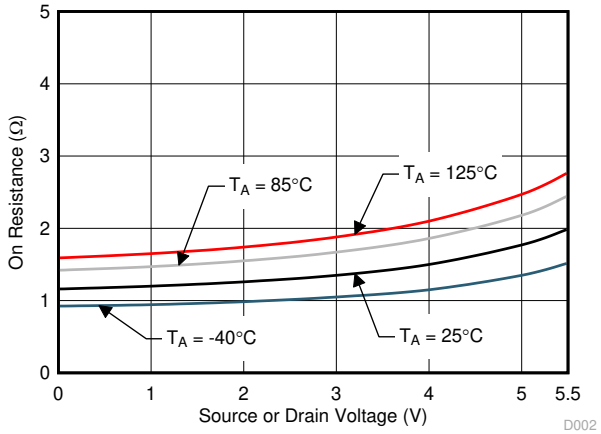
Typical Characteristics

At T_A = 25°C, V_{DD} = 3.3 V (unless otherwise noted).



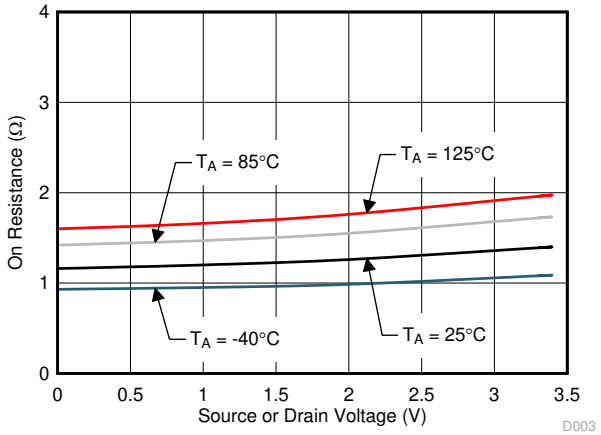
T_A = 25°C

図 6-1. On-Resistance vs Source or Drain Voltage



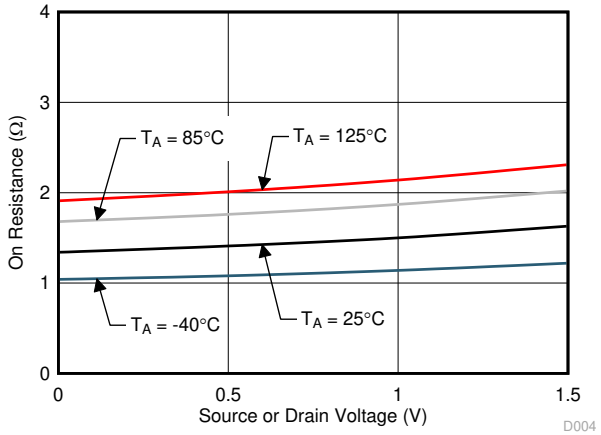
V_{DD} = 5.5 V

図 6-2. On-Resistance vs Source or Drain Voltage



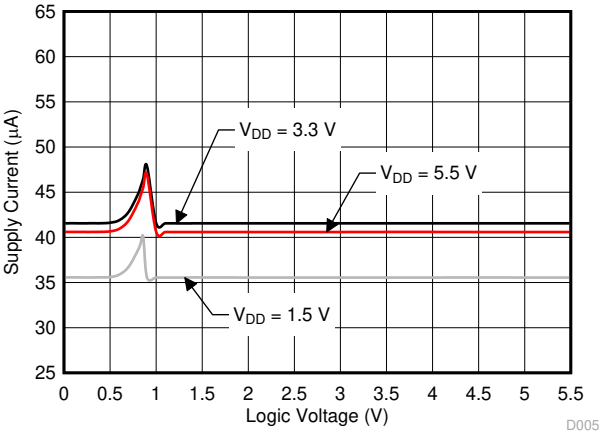
V_{DD} = 3.3 V

図 6-3. On-Resistance vs Source or Drain Voltage



V_{DD} = 1.5 V

図 6-4. On-Resistance vs Source or Drain Voltage



T_A = 25°C

図 6-5. Supply Current vs Logic Voltage

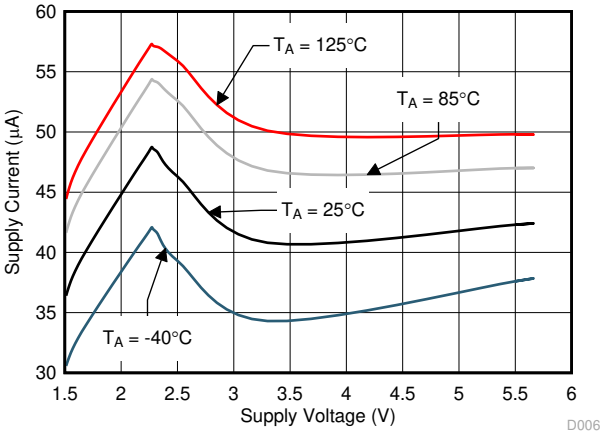
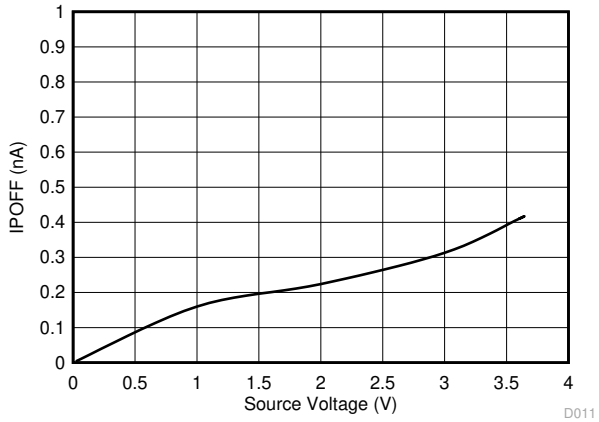


図 6-6. Supply Current vs Supply Voltage

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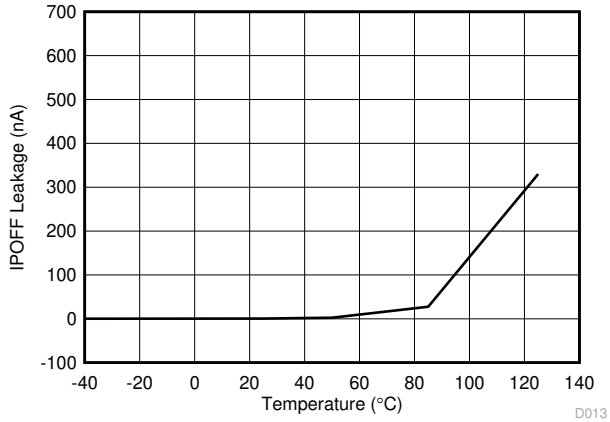
Typical Characteristics

At T_A = 25°C, V_{DD} = 3.3 V (unless otherwise noted).



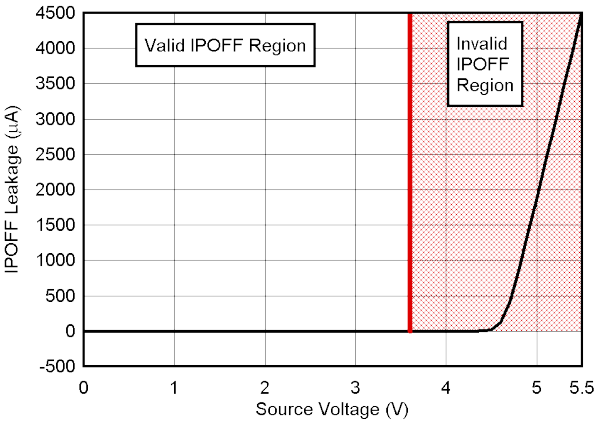
T_A = 25°C

図 6-7. IPOFF Leakage vs Source or Drain Voltage



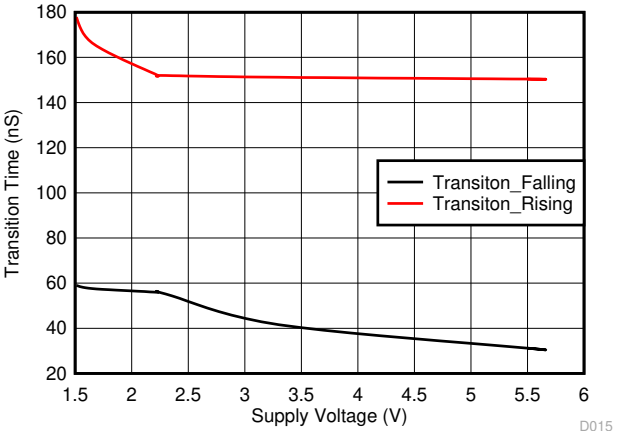
V_{Source} = 3.6 V
V_{Drain} = 0 V

図 6-8. IPOFF Leakage vs Temperature



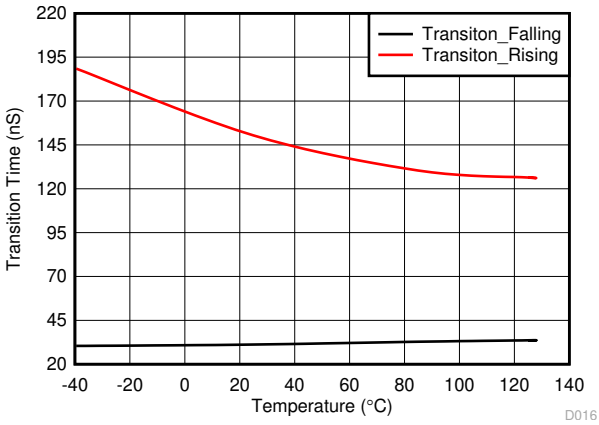
T_A = 25°C
R_L = 200 Ω

図 6-9. IPOFF Leakage vs Source or Drain Voltage



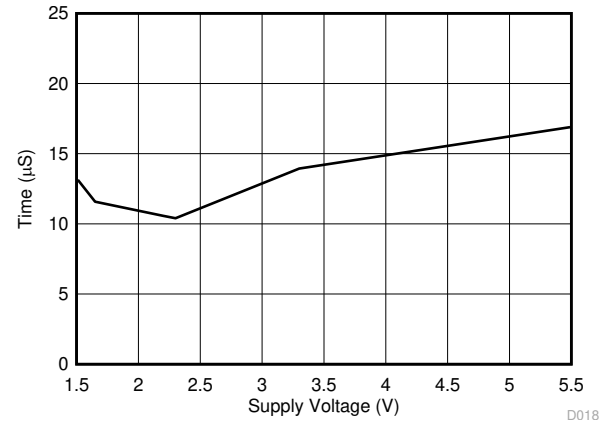
T_A = 25°C

図 6-10. $T_{TRANSITION}$ vs Supply Voltage



V_{DD} = 5.5 V

図 6-11. $T_{TRANSITION}$ vs Temperature



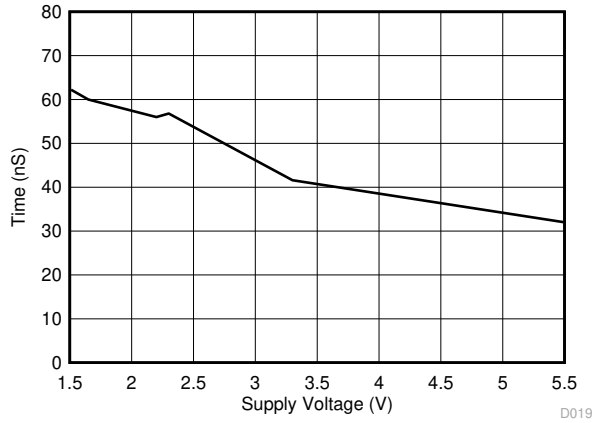
T_A = 25°C

図 6-12. $T_{ON\ (EN)}$ vs Supply Voltage

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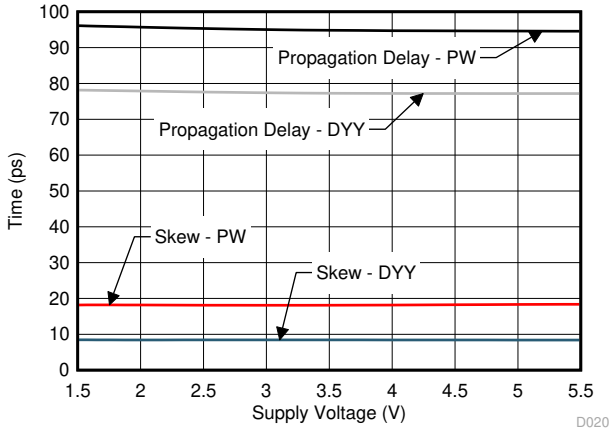
Typical Characteristics

At T_A = 25°C, V_{DD} = 3.3 V (unless otherwise noted).



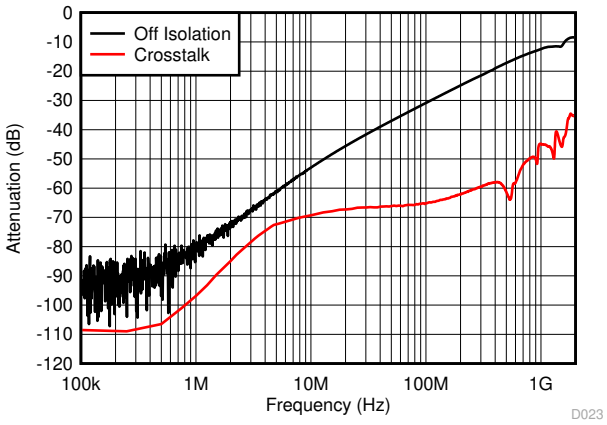
T_A = 25°C

図 6-13. $T_{OFF\ (EN)}$ vs Supply Voltage



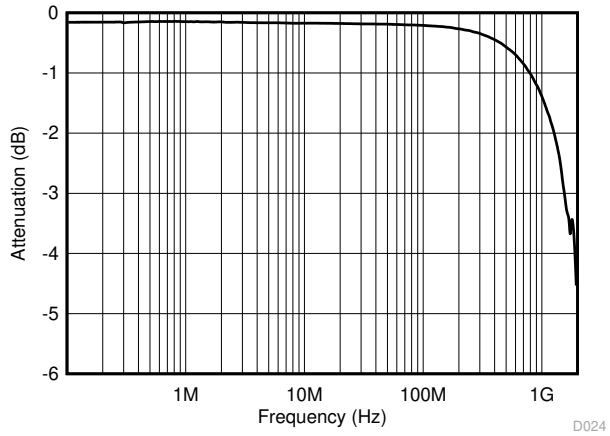
T_A = 25°C

図 6-14. Skew and Propagation Delay vs Supply Voltage



T_A = 25°C
V_{DD} = 3.3 V

図 6-15. Off Isolation and Crosstalk vs Frequency



T_A = 25°C
V_{DD} = 1.5 V to 5.5 V

図 6-16. On-Response vs Frequency

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7 Parameter Measurement Information

7.1 On-Resistance

The on-resistance of a device is the ohmic resistance between the source (Sx) and drain (Dx) pins of the device. The on-resistance varies with input voltage and supply voltage. The symbol R_{ON} is used to denote on-resistance. The measurement setup used to measure R_{ON} is shown in 図 7-1. Voltage (V) and current (I_{SD}) are measured using this setup, and R_{ON} is computed with $R_{ON} = V / I_{SD}$ as shown in the following figure.

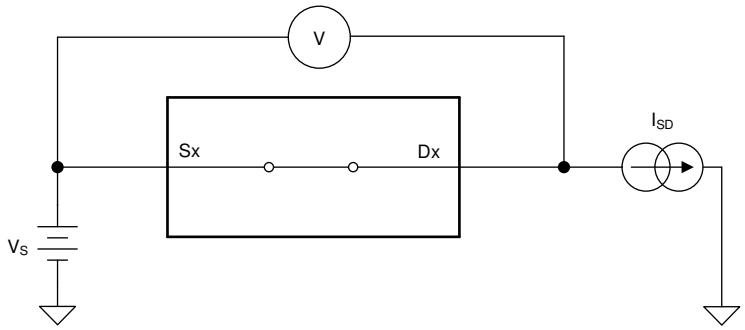


図 7-1. On-Resistance Measurement Setup

7.2 Off-Leakage Current

Source leakage current is defined as the leakage current flowing into or out of the source pin when the switch is off. This current is denoted by the symbol $I_{S\ (OFF)}$.

Drain leakage current is defined as the leakage current flowing into or out of the drain pin when the switch is off. This current is denoted by the symbol $I_{D\ (OFF)}$.

The setup used to measure both off-leakage currents is shown in 図 7-2.

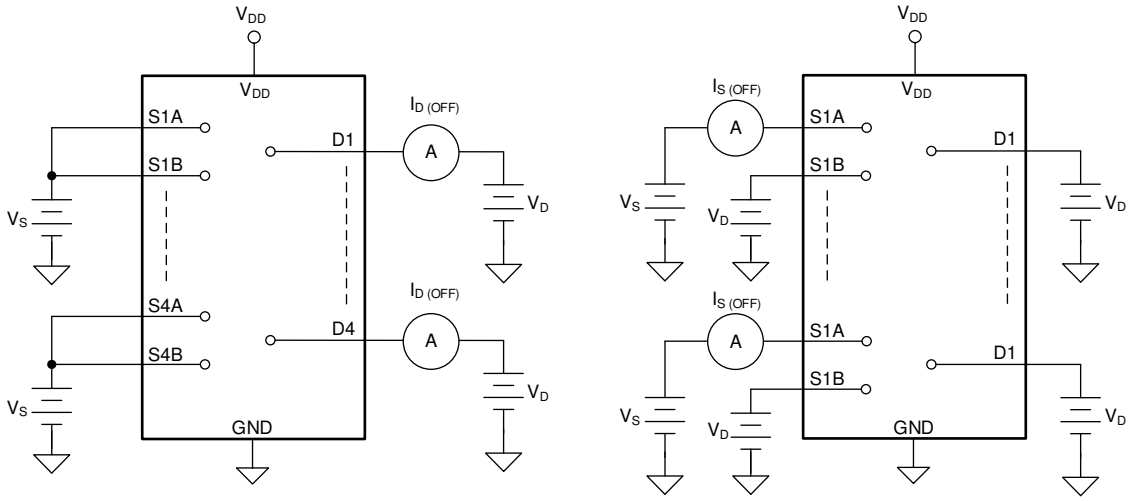


図 7-2. Off-Leakage Measurement Setup

7.3 On-Leakage Current

Source on-leakage current is defined as the leakage current flowing into or out of the source pin when the switch is on. This current is denoted by the symbol $I_{S\ (ON)}$.

Drain on-leakage current is defined as the leakage current flowing into or out of the drain pin when the switch is on. This current is denoted by the symbol $I_{D\ (ON)}$.

Either the source pin or drain pin is left floating during the measurement. 図 7-3 shows the circuit used for measuring the on-leakage current, denoted by $I_{S(ON)}$ or $I_{D(ON)}$.

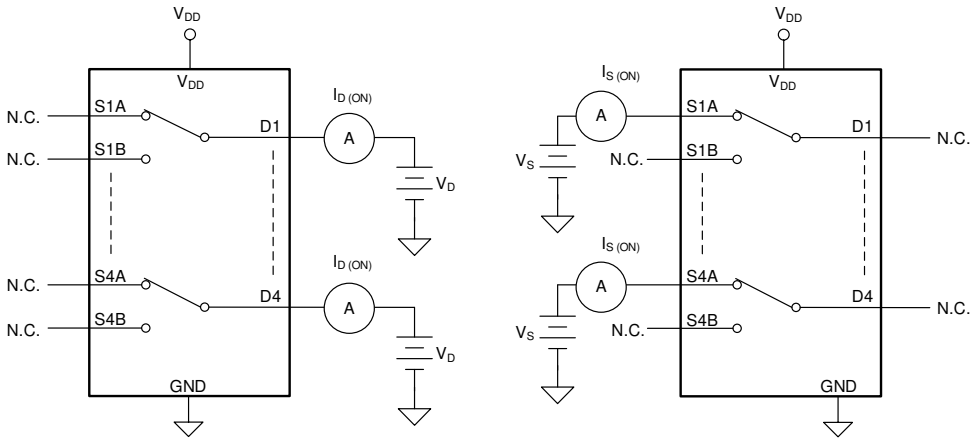


図 7-3. On-Leakage Measurement Setup

7.4 I_{POFF} Leakage Current

I_{POFF} leakage current is defined as the leakage current flowing into or out of the source pin when the device is powered off. This current is denoted by the symbol I_{POFF}.

The setup used to measure both I_{POFF} leakage current is shown in 図 7-4.

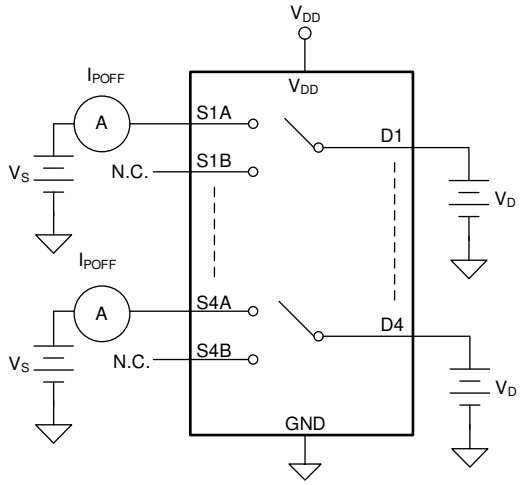


図 7-4. I_{POFF} Leakage Measurement Setup

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7.5 Transition Time

Transition time is defined as the time taken by the output of the device to rise or fall 10% after the select signal has risen or fallen past the logic threshold. The 10% transition measurement is utilized to provide the timing of the device. The time constant from the load resistance and load capacitance can be added to the transition time to calculate system level timing. 図 7-5 shows the setup used to measure transition time, denoted by the symbol $t_{TRANSITION}$.

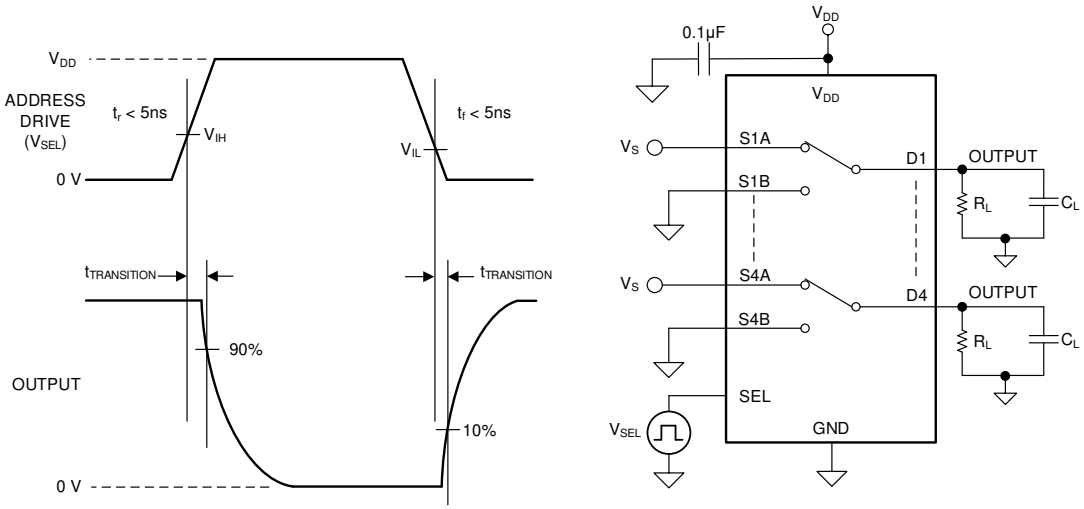


図 7-5. Transition-Time Measurement Setup

7.6 $t_{ON\ (EN)}$ and $t_{OFF\ (EN)}$ Time

The $t_{ON\ (EN)}$ time is defined as the time taken by the output of the device to rise to 90% after the enable has fallen past the logic threshold. The 90% measurement is used to provide the timing of the device being enabled in the system. 図 7-6 shows the setup used to measure the enable time, denoted by the symbol $t_{ON\ (EN)}$.

The $t_{OFF\ (EN)}$ time is defined as the time taken by the output of the device to fall to 90% after the enable has fallen past the logic threshold. The 90% measurement is used to provide the timing of the device being disabled in the system. 図 7-6 shows the setup used to measure enable time, denoted by the symbol $t_{OFF\ (EN)}$.

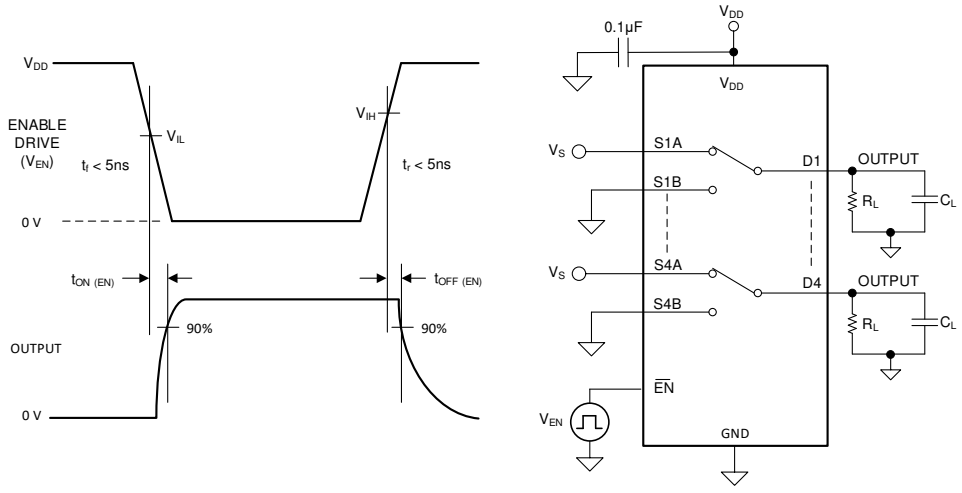


図 7-6. $t_{ON\ (EN)}$ and $t_{OFF\ (EN)}$ Time Measurement Setup

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7.7 $t_{ON\ (VDD)}$ and $t_{OFF\ (VDD)}$ Time

The $t_{ON\ (VDD)}$ time is defined as the time taken by the output of the device to rise to 90% after the supply has risen past the supply threshold. The 90% measurement is used to provide the timing of the device turning on in the system. 図 7-7 shows the setup used to measure turn on time, denoted by the symbol $t_{ON\ (VDD)}$.

The $t_{OFF\ (VDD)}$ time is defined as the time taken by the output of the device to fall to 90% after the supply has fallen past the supply threshold. The 90% measurement is used to provide the timing of the device turning off in the system. 図 7-7 shows the setup used to measure turn off time, denoted by the symbol $t_{OFF\ (VDD)}$.

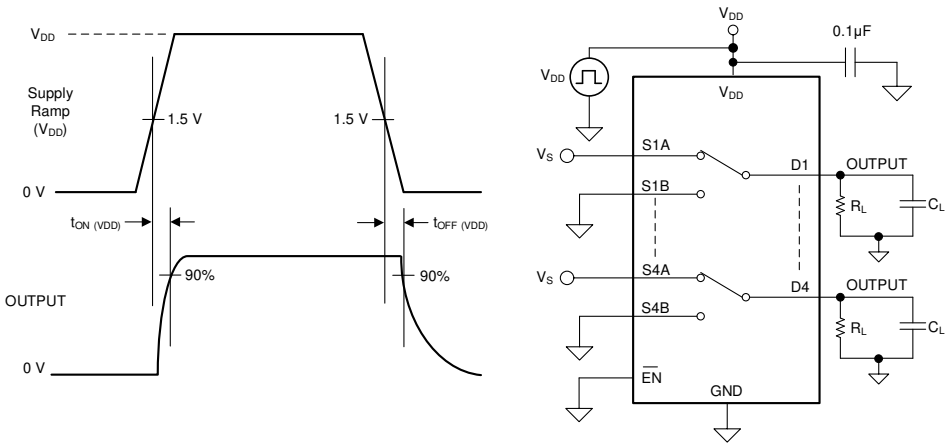


図 7-7. $t_{ON\ (VDD)}$ and $t_{OFF\ (VDD)}$ Time Measurement Setup

7.8 Break-Before-Make Delay

Break-before-make delay is a safety feature that prevents two inputs from connecting when the device is switching. The output first breaks from the on-state switch before making the connection with the next on-state switch. The time delay between the *break* and the *make* is known as break-before-make delay. 図 7-8 shows the setup used to measure break-before-make delay, denoted by the symbol $t_{OPEN(BBM)}$.

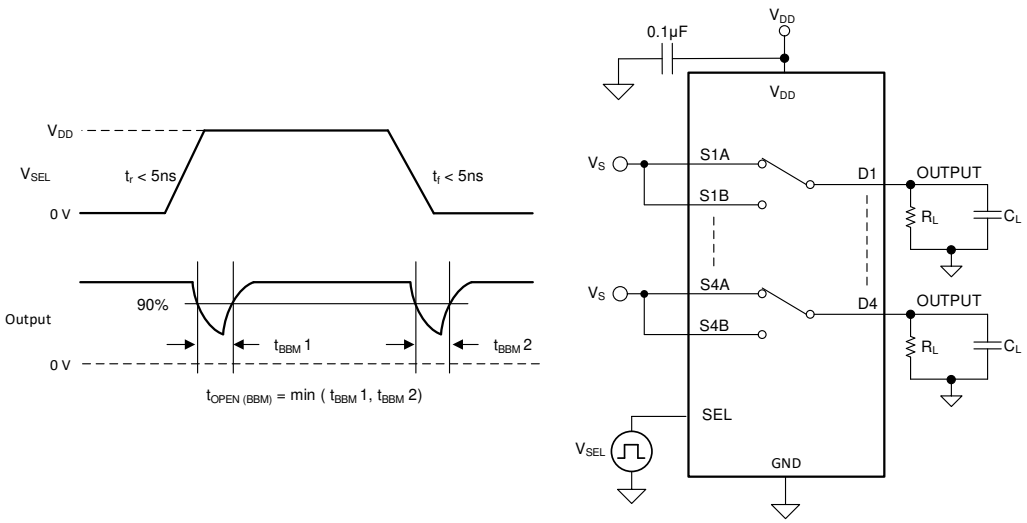


図 7-8. Break-Before-Make Delay Measurement Setup

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7.9 Propagation Delay

Propagation delay is defined as the time taken by the output of the device to rise or fall 50% after the input signal has risen or fallen past the 50% threshold. 図 7-9 shows the setup used to measure propagation delay, denoted by the symbol t_{PD}.

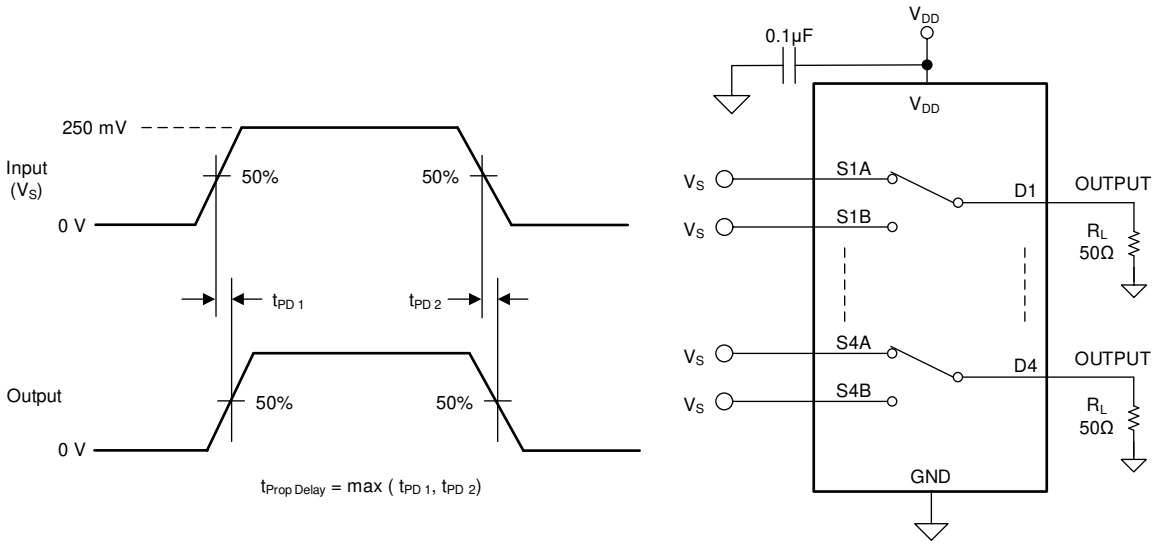


図 7-9. Propagation Delay Measurement Setup

7.10 Skew

Skew is defined as the difference between propagation delays of any two outputs of the same device. The skew measurement is taken from the output of one channel rising or falling past 50% to a second channel rising or falling past the 50% threshold when the input signals are switched at the same time. 図 7-10 shows the setup used to measure skew, denoted by the symbol t_{SK}.

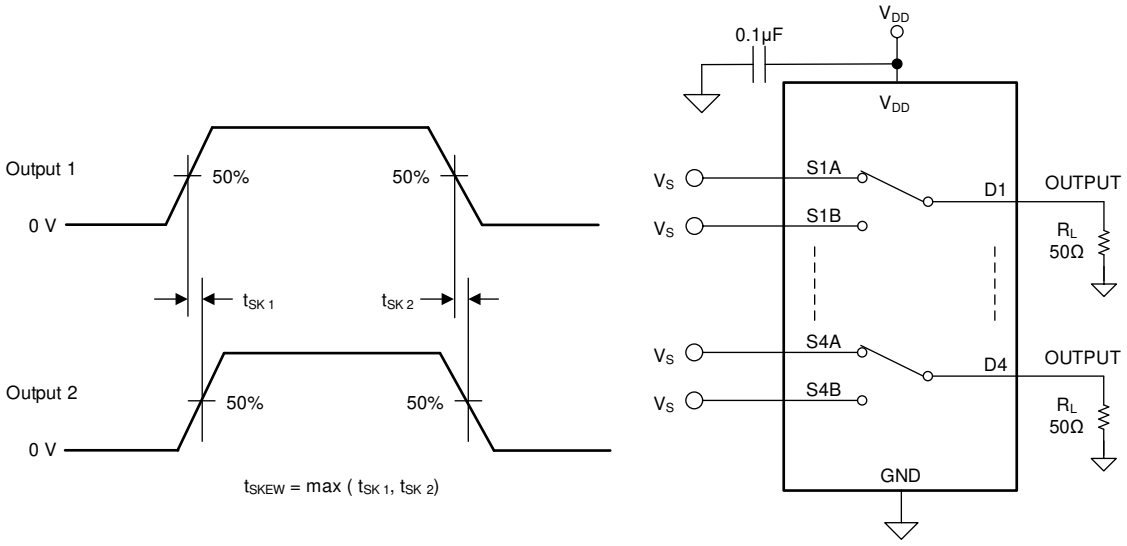


図 7-10. Skew Measurement Setup

7.11 Charge Injection

The amount of charge injected into the source or drain of the device during the falling or rising edge of the gate signal is known as charge injection, and is denoted by the symbol Q_C. 図 7-11 shows the setup used to measure charge injection from source (Sx) to drain (Dx).

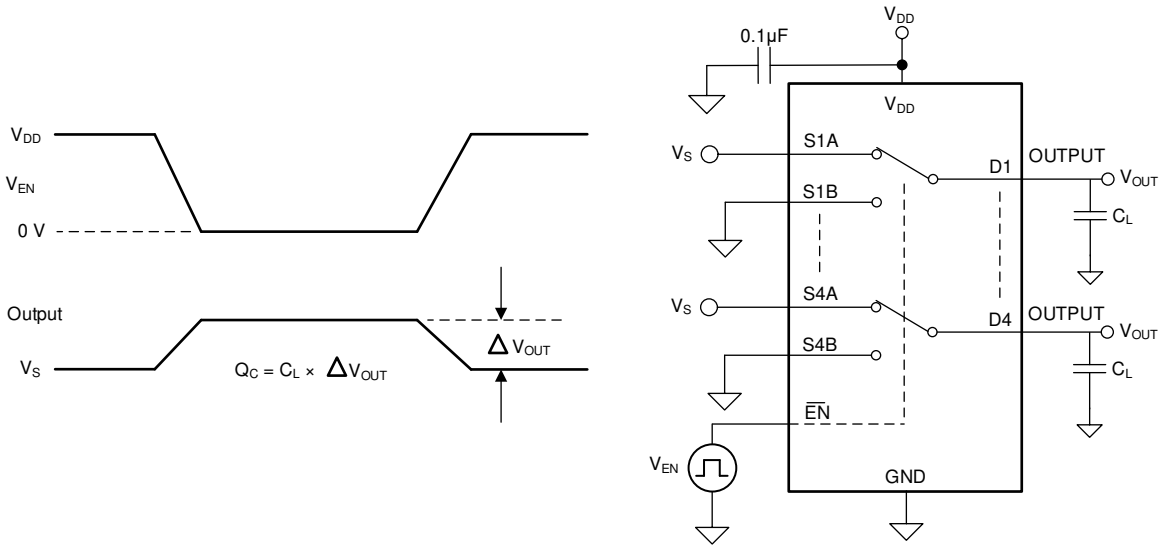


図 7-11. Charge-Injection Measurement Setup

7.12 Capacitance

The parasitic capacitance of the device is captured at the source (Sx), drain (Dx), and select (SELx) pins. The capacitance is measured in both the ON and OFF state and is denoted by the symbol C_{ON} and C_{OFF}. 図 7-12 shows the setup used to measure capacitance.

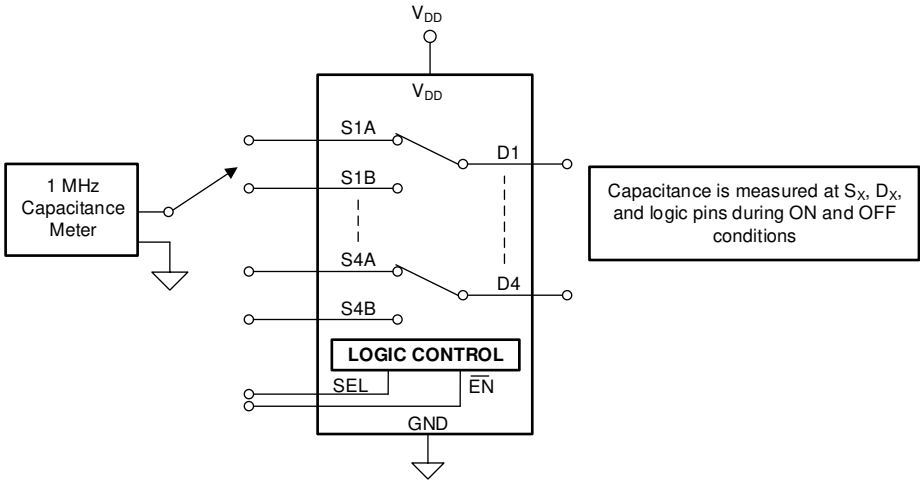


図 7-12. Capacitance Measurement Setup

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7.13 Off Isolation

Off isolation is defined as the ratio of the signal at the drain pin (Dx) of the device when a signal is applied to the source pin (Sx) of an off-channel. The characteristic impedance, Z_0, for the measurement is 50 Ω. 図 7-13 shows the setup used to measure off isolation. Use off isolation equation to compute off isolation.

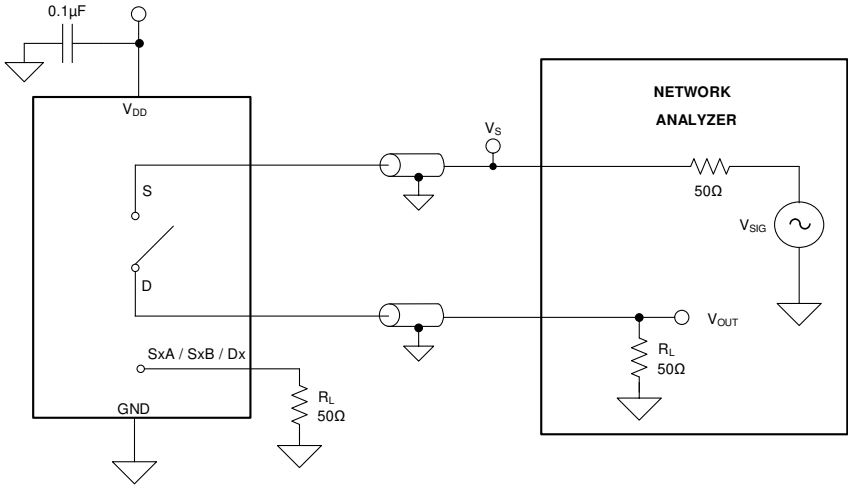


図 7-13. Off Isolation Measurement Setup

$$\text{Off Isolation} = 20 \cdot \text{Log}\left(\frac{V_{OUT}}{V_S}\right) \quad (1)$$

7.14 Channel-to-Channel Crosstalk

Crosstalk is defined as the ratio of the signal at the drain pin (Dx) of a different channel, when a signal is applied at the source pin (Sx) of an on-channel. The characteristic impedance, Z_0, for the measurement is 50 Ω. 図 7-14 shows the setup used to measure, and the equation used to compute crosstalk.

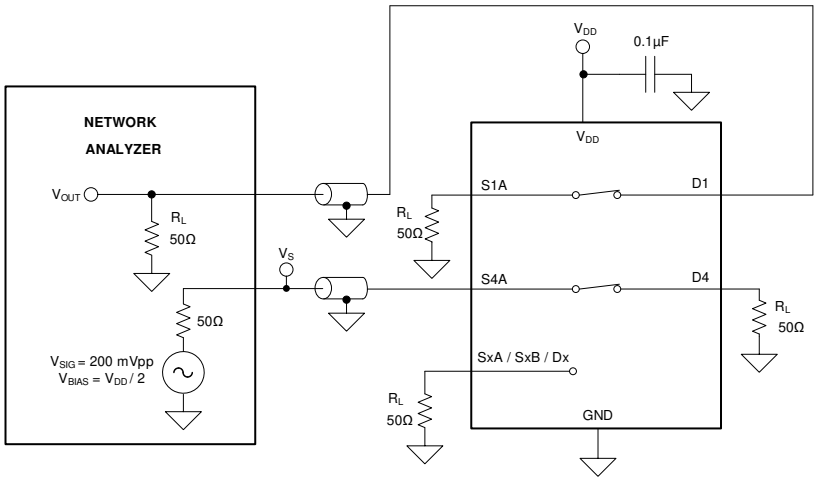


図 7-14. Channel-to-Channel Crosstalk Measurement Setup

$$\text{Channel-to-Channel Crosstalk} = 20 \cdot \text{Log}\left(\frac{V_{OUT}}{V_S}\right) \quad (2)$$

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7.15 Bandwidth

Bandwidth is defined as the range of frequencies that are attenuated by less than 3 dB when the input is applied to the source pin (Sx) of an on-channel, and the output is measured at the drain pin (Dx) of the device. The characteristic impedance, Z_0, for the measurement is 50 Ω. 図 7-15 shows the setup used to measure bandwidth.

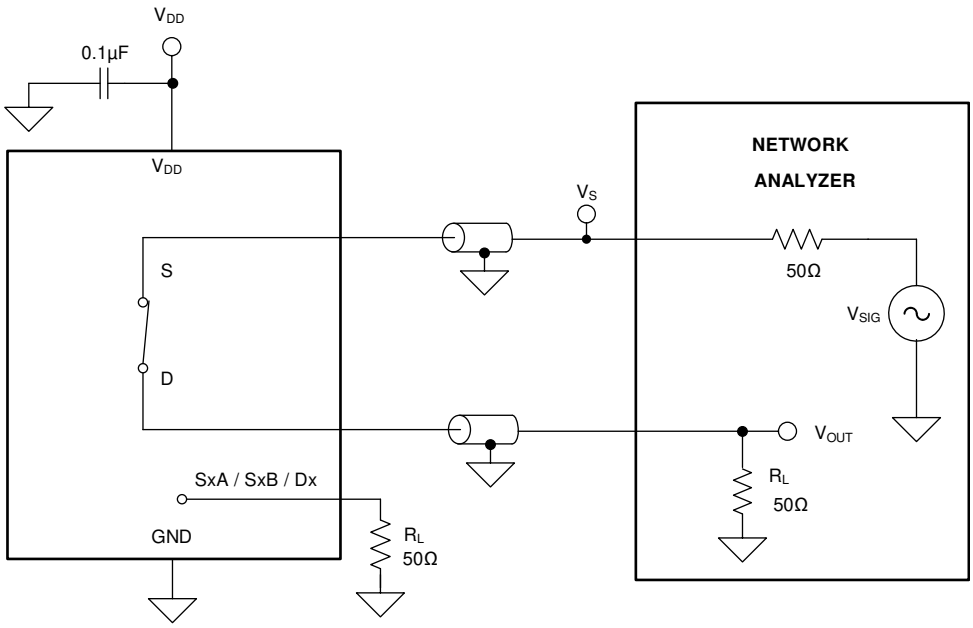


図 7-15. Bandwidth Measurement Setup

$$Attenuation = 20 \times Log\left(\frac{V_{OUT}}{V_S}\right) \quad (3)$$

8 Detailed Description

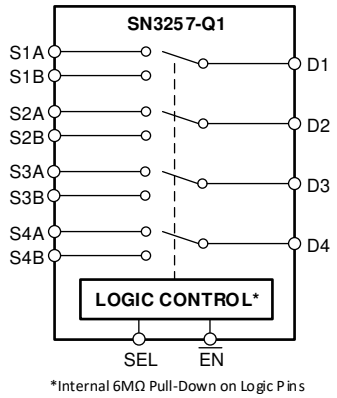
8.1 Overview

The SN3257-Q1 is an automotive qualified 2:1 (SPDT) 4-channel switch with powered-off protection up to 3.6 V. Wide operating supply of 1.5 V to 5.5 V allows for use in applications where different supply voltages are available. The device supports bidirectional analog and digital signals on the source (SxA, SxB) and drain (Dx) pins. The wide bandwidth of this switch allows little or no attenuation of high-speed signals with minimum propagation delay.

The enable ($\overline{EN}$) pin is an active-low logic pin that controls the connection between the source (SxA, SxB) and drain (Dx) pins of the device. The select pin (SEL) controls the state of all four channels of the SN3257-Q1 and determines which source pin is connected to the drain. Fail-Safe Logic circuitry allows voltages on the logic control pins to be applied before the supply pin, protecting the device from potential damage. All logic control inputs have 1.8 V logic compatible thresholds, ensuring both TTL and CMOS logic compatibility when operating in the valid supply voltage range.

Powered-off protection up to 3.6 V on the signal path of the SN3257-Q1 provides isolation when the supply voltage is removed (V_{DD} = 0 V). Without this protection feature, the system can back-power the supply rail through an internal ESD diode and cause potential damage to the system.

8.2 Functional Block Diagram



8.3 Feature Description

8.3.1 Bidirectional Operation

The SN3257-Q1 conducts equally well from source (SxA, SxB) to drain (Dx) or from drain (Dx) to source (SxA, SxB). Each channel has very similar characteristics in both directions and supports both analog and digital signals.

8.3.2 Beyond Supply Operation

When the SN3257-Q1 is powered from 1.5 V to 5.5 V, the valid signal path input or output voltage ranges from GND to V_{DD} x 2, with a maximum input or output voltage of 5.5 V.

Example 1: If the SN3257-Q1 is powered at 1.5 V, the signal range is 0 V to 3 V.

Example 2: If the SN3257-Q1 is powered at 2.5 V, the signal range is 0 V to 5.0 V.

Example 2: If the SN3257-Q1 is powered at 3.6 V, the signal range is 0 V to 5.5 V.

Example 3: If the SN3257-Q1 is powered at 5.5 V, the signal range is 0 V to 5.5 V.

Other voltage levels not mentioned in the examples support Beyond Supply Operation as long as the supply voltage falls within the recommended operation conditions of 1.5 V to 5.5 V.

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8.3.3 1.8 V Logic Compatible Inputs

The SN3257-Q1 has 1.8-V logic compatible control inputs. Regardless of the V_{DD} voltage, the control input thresholds remain fixed, allowing a 1.8-V processor GPIO to control the SN3257-Q1 without the need for an external translator. This saves both space and BOM cost. For more information on 1.8 V logic implementations, refer to *Simplifying Design with 1.8 V logic Muxes and Switches.*

8.3.4 Powered-off Protection

Powered-off protection up to 3.6 V on the signal path of the SN3257-Q1 provides isolation when the supply voltage is removed (V_{DD} = 0 V). When the SN3257-Q1 is powered-off, the I/Os of the device remain in a high-Z state. Powered-off protection minimizes system complexity by removing the need for power supply sequencing on the signal path. The device performance remains within the leakage performance mentioned in the Electrical Specifications. For more information on powered-off protection, refer to *Eliminate Power Sequencing with Powered-off Protection Signal Switches*.

8.3.5 Fail-Safe Logic

The SN3257-Q1 has Fail-Safe Logic on the control input pins (SELx) which allows for operation up to 5.5 V, regardless of the state of the supply pin. This feature allows voltages on the control pins to be applied before the supply pin, protecting the device from potential damage. Fail-Safe Logic minimizes system complexity by removing the need for power supply sequencing on the logic control pins. For example, the Fail-Safe Logic feature allows the select pins of the SN3257-Q1 to be ramped to 5.5 V while V_{DD} = 0 V. Additionally, the feature enables operation of the SN3257-Q1 with V_{DD} = 1.5 V while allowing the select pins to interface with a logic level of another device up to 5.5 V.

8.3.6 Integrated Pull-Down Resistors

The SN3257-Q1 has internal weak pull-down resistors (6 MΩ) to GND to ensure the logic pins are not left floating. This feature integrates up to four external components and reduces system size and cost.

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8.4 Device Functional Modes

The enable ($\overline{EN}$) pin is an active-low logic pin that controls the connection between the source (SxA, SxB) and drain (Dx) pins of the device. When the enable pin is pulled high, all switches are turned off. When the enable pin is pulled low, the select pin controls the signal path selection. The select pin (SEL) controls the state of all four channels of the SN3257-Q1 and determines which source pin is connected to the drain pins. When the select pin is pulled low, the SxA pin conducts to the corresponding Dx pins. When the select pin is pulled high, the SxB pin conducts to the corresponding Dx pins. The SN3257-Q1 logic pins have internal weak pull-down resistors (6 MΩ) to GND so that it powers-on in a known state.

The SN3257-Q1 can be operated without any external components except for the supply decoupling capacitors. Unused logic control pins should be tied to GND or V_{DD} to ensure the device does not consume additional current as highlighted in *Implications of Slow or Floating CMOS Inputs*. Unused signal path inputs (SxA, SxB, or Dx) should be connected to GND.

8.4.1 Truth Tables

表 8-1. SN3257-Q1 Truth Table

INPUTS		Selected Source Pins Connected To Drain Pins (Dx)
$\overline{EN}$	SEL	
0	0	S1A connected to D1 S2A connected to D2 S3A connected to D3 S4A connected to D4
0	1	S1B connected to D1 S2B connected to D2 S3B connected to D3 S4B connected to D4
1	X(1)	Hi-Z (OFF)

(1) X denotes *do not care*.

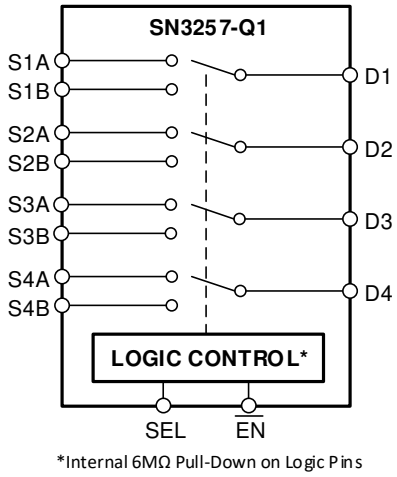


図 8-1. SN3257-Q1 Functional Block Diagram

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9 Application and Implementation

注

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9.1 Application Information

The SN3257-Q1 operates across a wide supply 1.5 V to 5.5 V and operating temperature range (–40°C to +125°C). The SN3257-Q1 supports a number of features that improve system performance such as 1.8 V logic compatibility, supports input voltages beyond supply, Fail-Safe Logic, and Powered-off Protetion up to 3.6 V. These features reduce system complexity, board size, and overall system cost.

9.2 Typical Application

Common applications that require the features of the SN3257-Q1 include multiplexing various protocols from a processor or MCU such as SPI, eMMC, I2S, or standard GPIO signals. The SN3257-Q1 provides superior isolation performance when the device is powered. The added benefit of powered-off protection allows a system to minimize complexity by eliminating the need for power sequencing in hot-swap and live insertion applications. 図 9-1 shows how to use the SN3257-Q1 to multiplex an SPI bus to multiple flash memory devices.

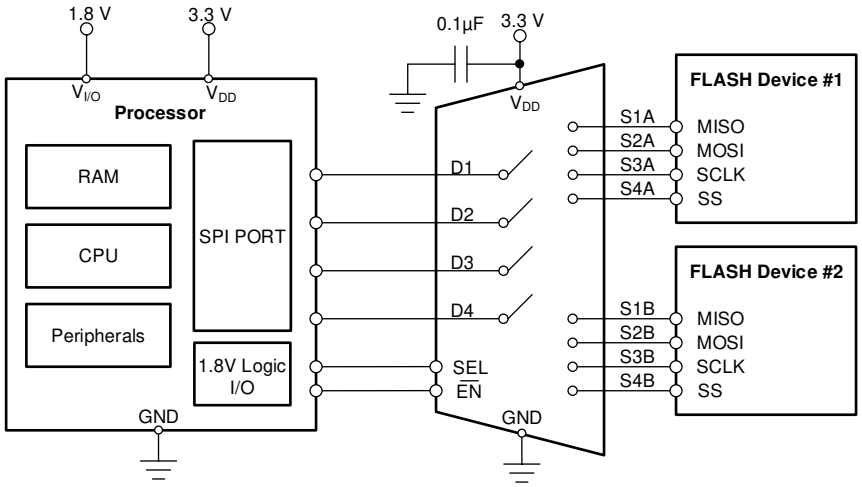


図 9-1. Multiplexing Flash Memory

9.2.1 Design Requirements

For this design example, use the parameters listed in 表 9-1.

表 9-1. Design Parameters

PARAMETERS	VALUES
Supply (V_{DD})	3.3 V
Input and Output signals	0 V to 3.3 V SPI
Control logic thresholds	1.8 V compatible

9.2.2 Detailed Design Procedure

The SN3257-Q1 can be operated without any external components except for the supply decoupling capacitors. The SN3257-Q1 has internal weak pull-down resistors (6 MΩ) to GND so that it powers-on with the switches in a known state. All inputs signals passing through the switch must fall within the recommended operating conditions of the SN3257-Q1 including signal range and continuous current. This design example can support SPI signals that range from 0 V to 3.3 V when the device is powered. This example can also utilize the Powered-off Protection feature and the inputs can range from 0 V to 3.6 V when V_{DD} = 0 V. The maximum continuous current can be 25 mA. Due to the voltage range and high speed capability, the SN3257-Q1 example is suitable for use in SPI, JTAG, and I2S applications.

9.2.3 Application Curves

Two important specifications when using a switch or multiplexer to pass signals are the device propagation delay and skew.

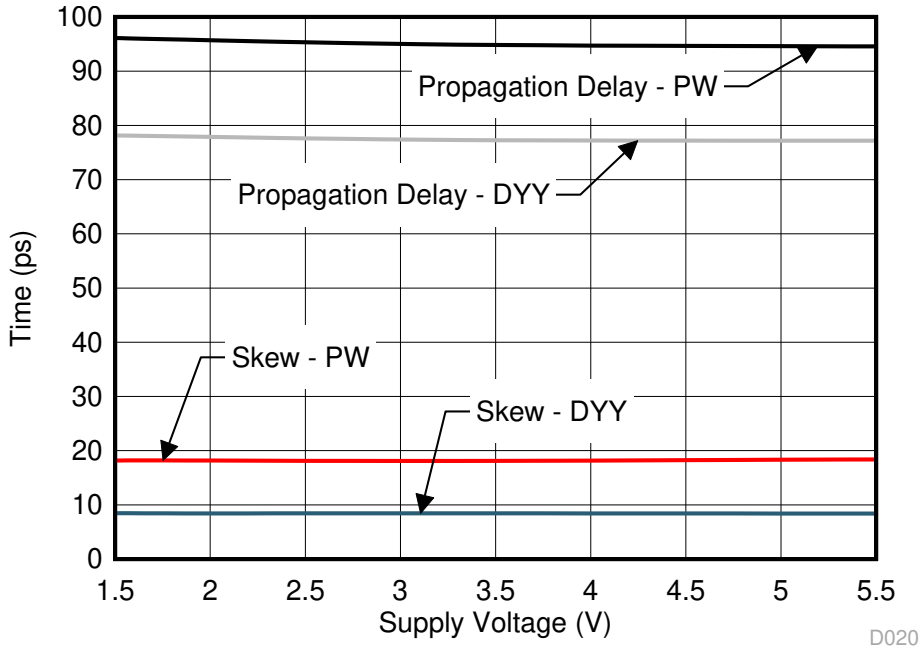


図 9-2. Propagation Delay and Skew Measurement

10 Power Supply Recommendations

The SN3257-Q1 operates across a wide supply range of 1.5 V to 5.5 V. Do not exceed the absolute maximum ratings because stresses beyond the listed ratings can cause permanent damage to the devices.

Power-supply bypassing improves noise margin and prevents switching noise propagation from the V_{DD} supply to other components. Good power-supply decoupling is important to achieve optimum performance. For improved supply noise immunity, use a supply decoupling capacitor ranging from 0.1 µF to 10 µF from the V_{DD} to ground. Place the bypass capacitors as close to the power supply pins of the device as possible using low-impedance connections. TI recommends using multi-layer ceramic chip capacitors (MLCCs) that offer low equivalent series resistance (ESR) and inductance (ESL) characteristics for power-supply decoupling purposes. For very sensitive systems, or for systems in harsh noise environments, avoiding the use of vias for connecting the capacitors to the device pins may offer superior noise immunity. The use of multiple vias in parallel lowers the overall inductance and is beneficial for connections to ground planes.

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11 Layout

11.1 Layout Guidelines

When a PCB trace turns a corner at a 90° angle, a reflection can occur. A reflection occurs primarily because of the change of width of the trace. At the apex of the turn, the trace width increases to 1.414 times the width. This increase upsets the transmission-line characteristics, especially the distributed capacitance and self–inductance of the trace which results in the reflection. Not all PCB traces can be straight and therefore some traces must turn corners. 図 11-1 shows progressively better techniques of rounding corners. Only the last example (BEST) maintains constant trace width and minimizes reflections.

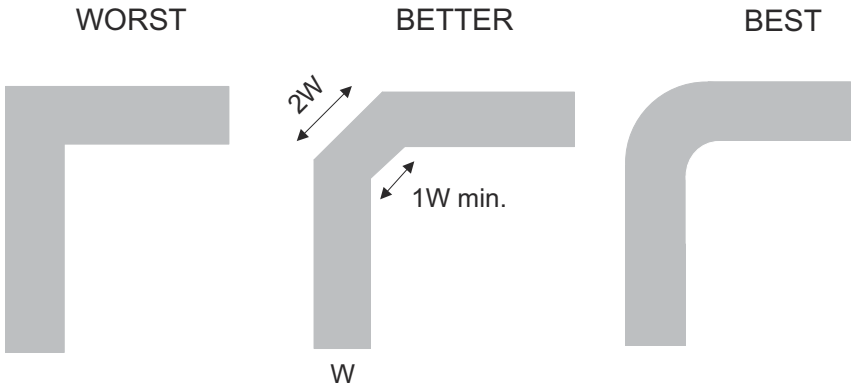


図 11-1. Trace Example

Route the high-speed signals using a minimum of vias and corners which reduces signal reflections and impedance changes. When a via must be used, increase the clearance size around it to minimize its capacitance. Each via introduces discontinuities in the signal's transmission line and increases the chance of picking up interference from the other layers of the board. Be careful when designing test points, through-hole pins are not recommended at high frequencies.

Do not route high speed signal traces under or near crystals, oscillators, clock signal generators, switching regulators, mounting holes, magnetic devices or ICs that use or duplicate clock signals.

Avoid stubs on the high-speed signals traces because they cause signal reflections.

Route all high-speed signal traces over continuous GND planes, with no interruptions.

Avoid crossing over anti-etch, commonly found with plane splits.

When working with high frequencies, a printed circuit board with at least four layers is recommended; two signal layers separated by a ground and power layer as shown in 図 11-2.

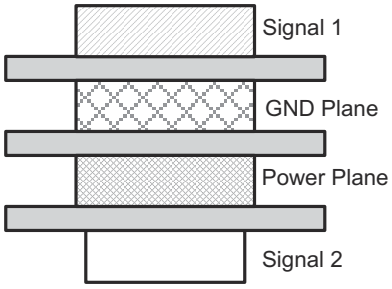


図 11-2. Example Layout

The majority of signal traces must run on a single layer, preferably Signal 1. Immediately next to this layer must be the GND plane, which is solid with no cuts. Avoid running signal traces across a split in the ground or power plane. When running across split planes is unavoidable, sufficient decoupling must be used. Minimizing the number of signal vias reduces EMI by reducing inductance at high frequencies.

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図 11-3 shows an example of a PCB layout with the SN3257-Q1. Some key considerations are:

Decouple the V_{DD} pin with a 0.1-µF capacitor, placed as close to the pin as possible. Make sure that the capacitor voltage rating is sufficient for the V_{DD} supply.

High-speed switches require proper layout and design procedures for optimum performance.

Keep the input lines as short as possible.

Use a solid ground plane to help reduce electromagnetic interference (EMI) noise pickup.

Do not run sensitive analog traces in parallel with digital traces. Avoid crossing digital and analog traces if possible, and only make perpendicular crossings when necessary.

11.2 Layout Example

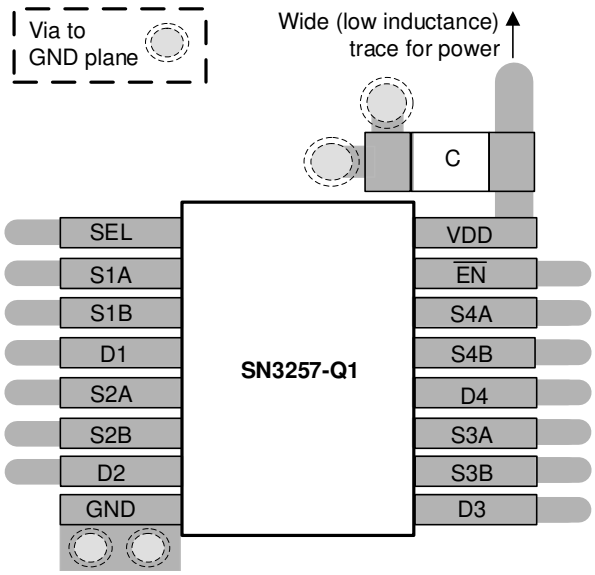


図 11-3. Example Layout

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12 Device and Documentation Support

12.1 Documentation Support

12.1.1 Related Documentation

For related documenation, see the following:

- Texas Instruments, *SN3257-Q1 Functional Safety FIT Rate, FMD, and Pin FMA* application report
- Texas Instruments, *Eliminate Power Sequencing with Powered-off Protection Signal Switches* application briefs
- Texas Instruments, *Simplifying Design with 1.8 V logic Muxes and Switches* application brief
- Texas Instruments, *System-Level Protection for High-Voltage Analog Multiplexers* application reports
- Texas Instruments, *Improve Stability Issues with Low CON Multiplexers* application brief
- Texas Instruments, *High-Speed Interface Layout Guidelines* application report
- Texas Instruments, *High-Speed Layout Guidelines* application report

12.2 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on ti.com. Click on *Subscribe to updates* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

12.3 サポート・リソース

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12.5 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

12.6 Glossary

TI Glossary	This glossary lists and explains terms, acronyms, and definitions.

13 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

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PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package | Pins	Package qty | Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
SN3257QDYYRQ1	Active	Production	SOT-23-THIN (DYY) | 16	3000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	SN3257
SN3257QDYYRQ1.A	Active	Production	SOT-23-THIN (DYY) | 16	3000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	SN3257
SN3257QPWRQ1	Active	Production	TSSOP (PW) | 16	2000 | LARGE T&R	Yes	NIPDAU | SN	Level-1-260C-UNLIM	-40 to 125	SN3257
SN3257QPWRQ1.A	Active	Production	TSSOP (PW) | 16	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	SN3257

(1) **Status:** For more details on status, see our product life cycle.

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

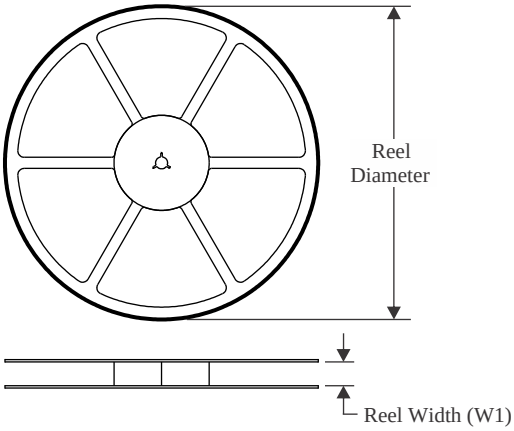
Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

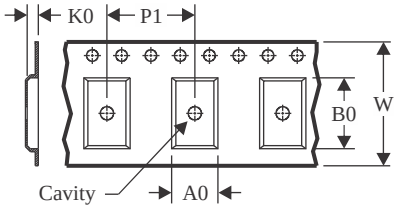
In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

TAPE AND REEL INFORMATION

REEL DIMENSIONS

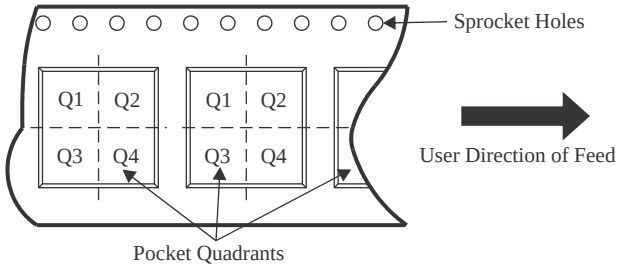


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

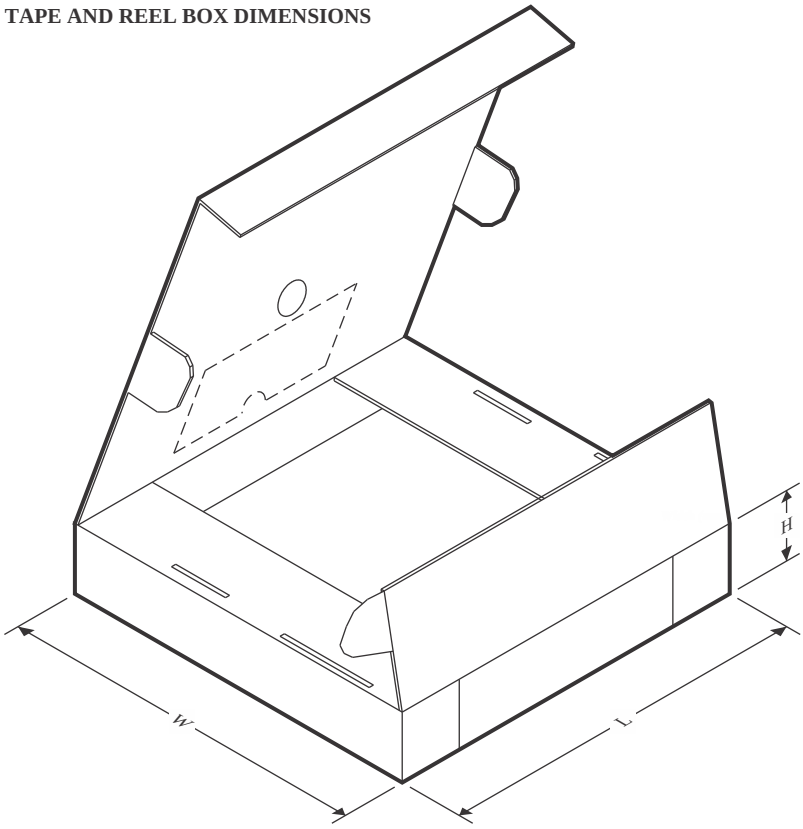
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN3257QDYYRQ1	SOT-23-THIN	DYY	16	3000	330.0	12.4	4.8	3.6	1.6	8.0	12.0	Q3
SN3257QPWRQ1	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

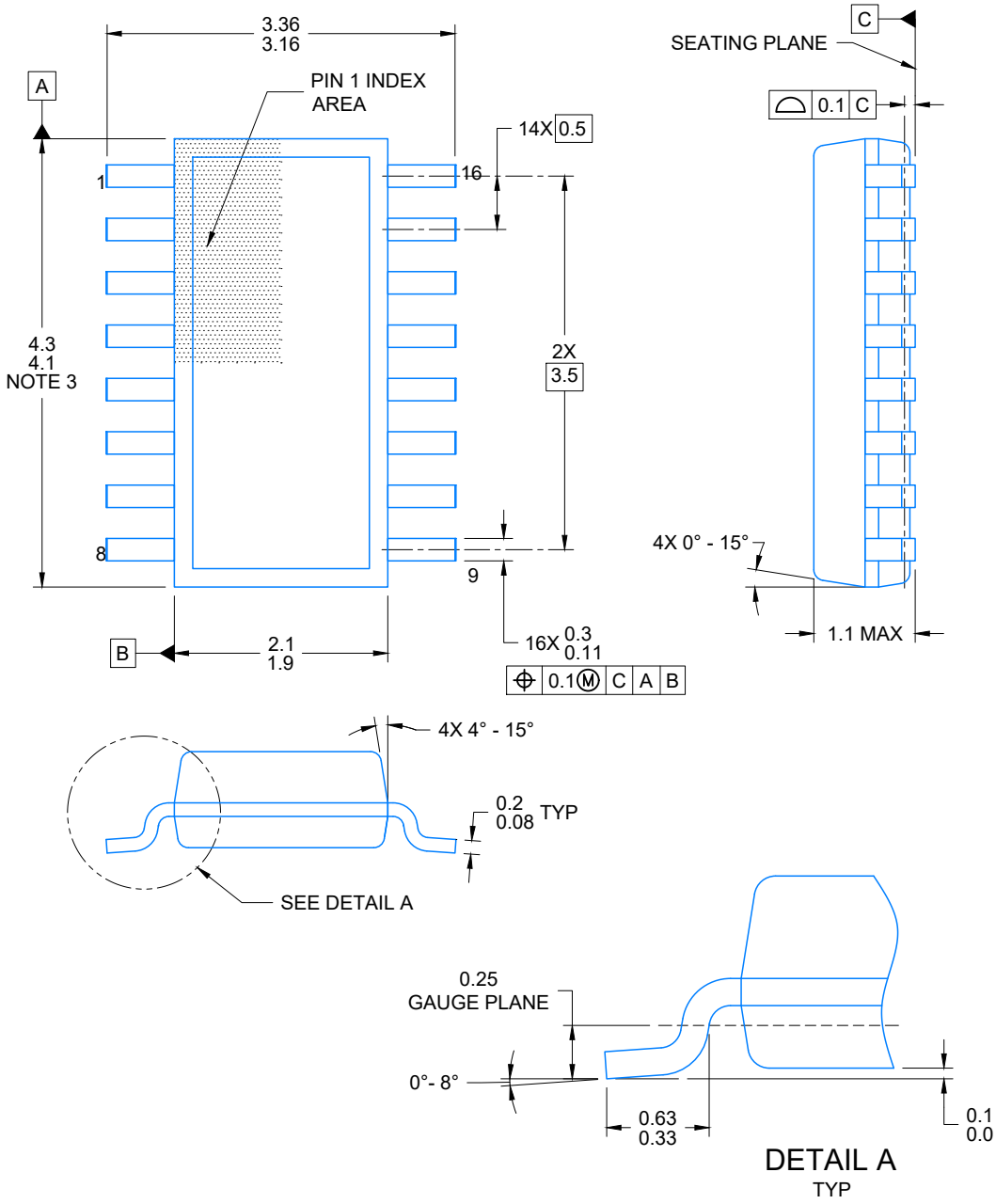
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN3257QDYYRQ1	SOT-23-THIN	DYY	16	3000	336.6	336.6	31.8
SN3257QPWRQ1	TSSOP	PW	16	2000	353.0	353.0	32.0

PACKAGE OUTLINE

DYY0016A

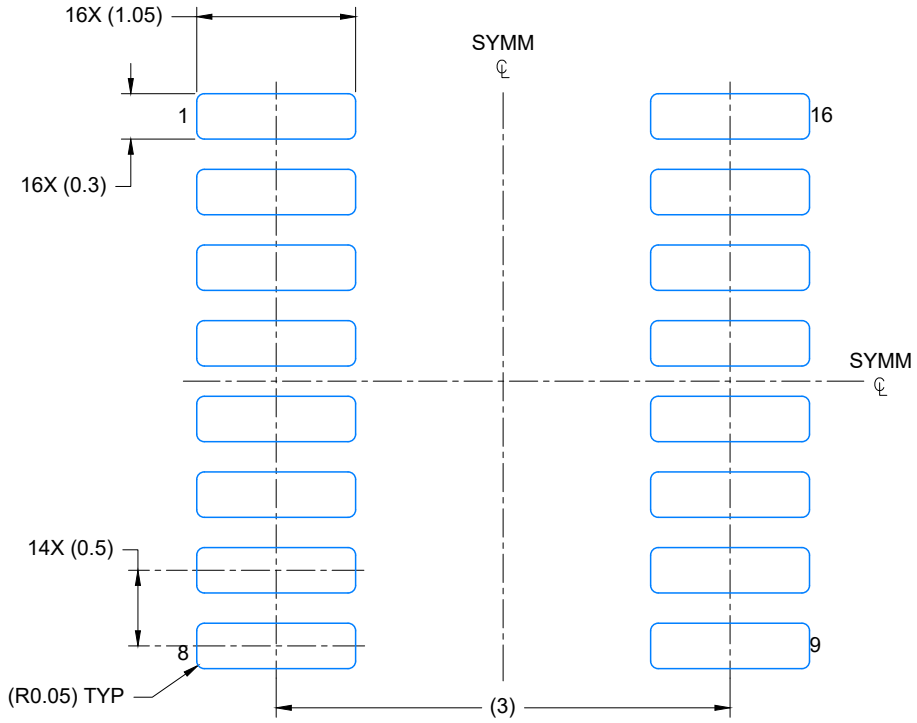
SOT-23-THIN - 1.1 mm max height

PLASTIC SMALL OUTLINE

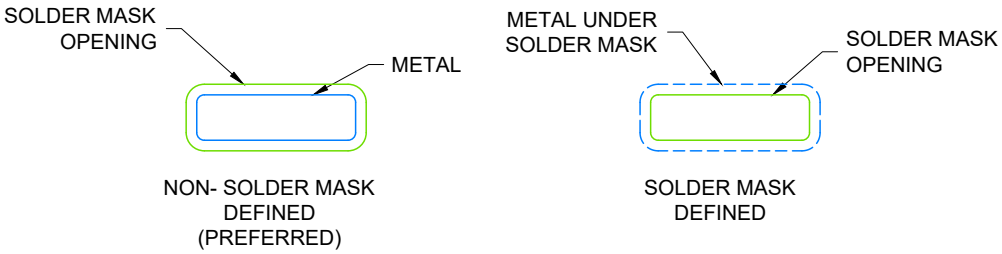


NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.50 per side.
5. Reference JEDEC Registration MO-345, Variation AA



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 20X



SOLDER MASK DETAILS

4224642/D 07/2024

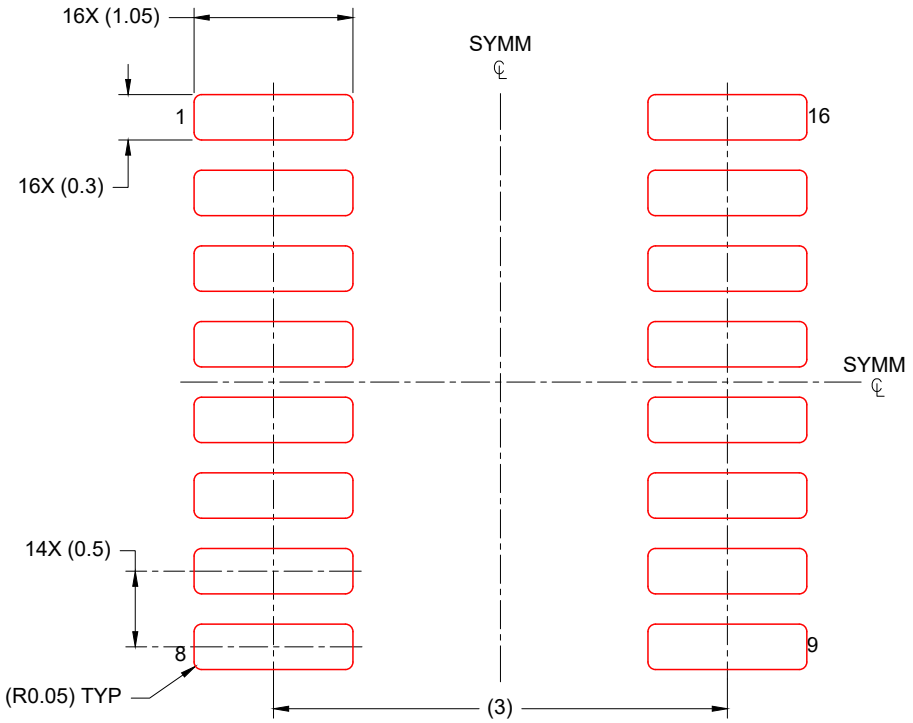
NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

SOT-23-THIN - 1.1 mm max height

PLASTIC SMALL OUTLINE



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 20X

4224642/D 07/2024

NOTES: (continued)

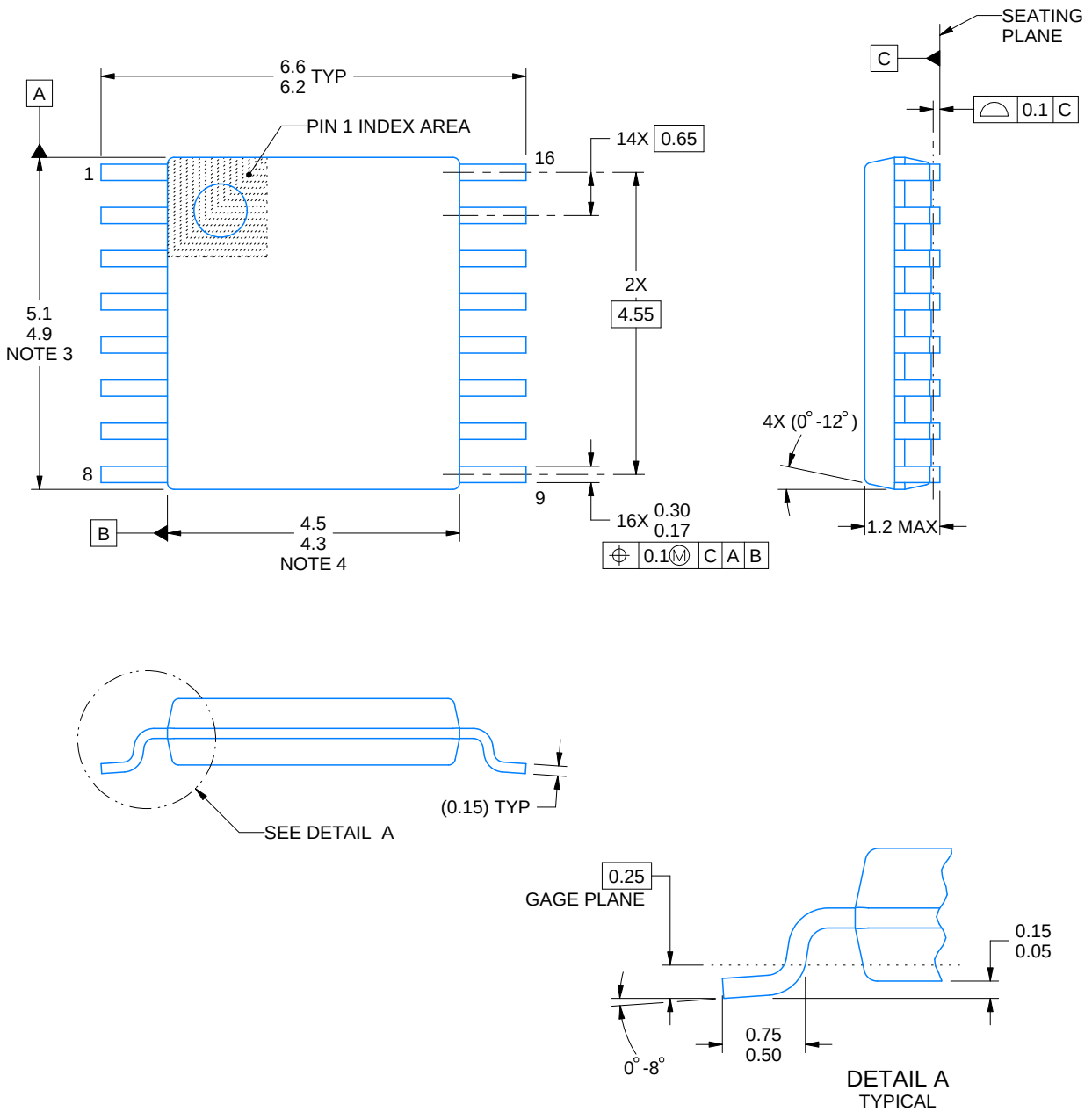
8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

PACKAGE OUTLINE

PW0016A

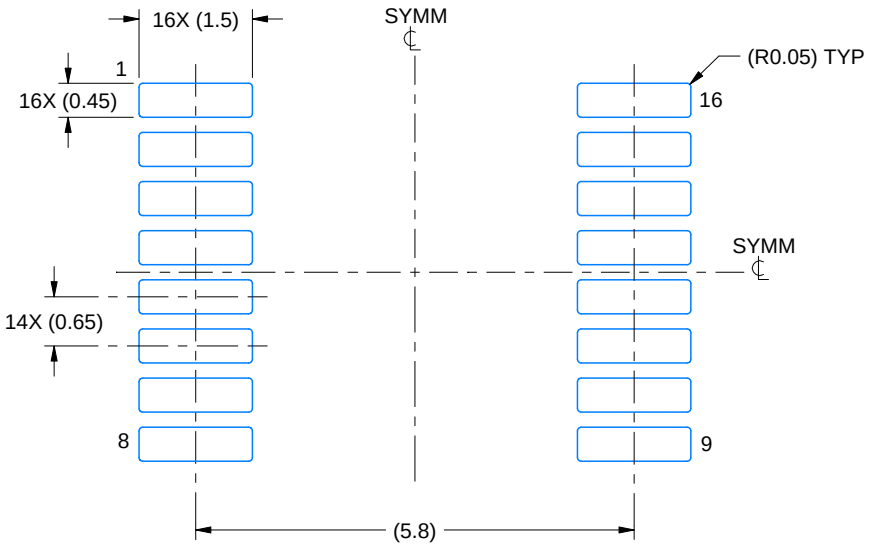
TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X

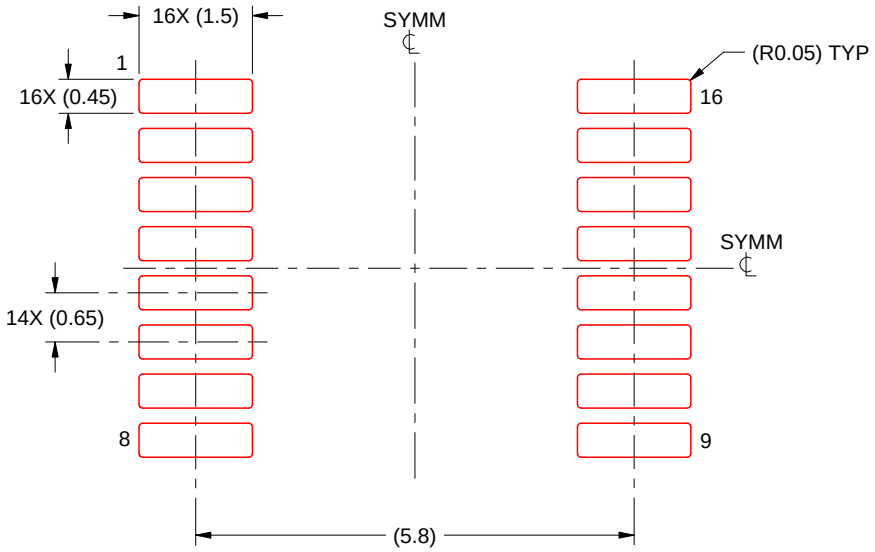


SOLDER MASK DETAILS

4220204/B 12/2023

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

4220204/B 12/2023

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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最終更新日：2025 年 10 月